IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 10/791,191

Filed: March 2, 2004

For: METHOD OF IMPROVING COPPER

INTERCONNECTS OF

SEMICONDUCTOR DEVICES FOR

BONDING

Confirmation No.: 1968

Examiner: A. Roman

Group Art Unit: 2812

Attorney Docket No.: 2269-3854.3US

(98-0854.03/US)

VIA ELECTRONIC FILING June 27, 2007

AMENDMENT

Mail Stop Amendment Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed April 19, 2007, the three-month shortened statutory period for response to which expires on July 19, 2007.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.